

# EL.BO. Service

## Electronic packaging

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### Metal Out Product Specifications

#### ELS-505

Static Shielding Material  
Complies with EN 61340-5-1  
and ANSI/ESD S20.20

#### Construction:

Conductive coating
<b>Metal</b>
Polyester
<b>Polyethylene</b>
Anti-Static

<u>Physical Properties</u>	<u>Test method</u>	<u>Specifications</u>
Thickness	LAB # 001	2.9 mil $\pm$ 10%
Puncture Resistance	FTMS 101C method 2065	12 lbs
Yield	LAB # 002	9,200 sqin/lb
Tensile Strength	ASTM D-882	25 lbs / in
Puncture Resistance	FTMS 101C method 2065	> 12 lbs
Seam Strength	ASTM D-882	> 12 lbs / in
Play Bond	ASTM D-1876-95	MD > 2.0 lbs.p / in
Haze	ASTM D-1003	4 %
Optical Density	McBeth	0.35 – 0.45
Light Transmission	ASTM D -1003	> 40 %
Abrasion Resistance	LAB#004	Good
Heat Seal		375°F 1 sec. 60 psi
Blocking	LAB#003	None

<u>Electrical Properties</u>	<u>Test Method</u>	<u>Specifications</u>
Surface Resistance PE layer	IEC 61340-2-3 15 % RH	< 10 <sup>11</sup> Ohm
Surface Resistance Conductive Coating	IEC 61340-2-3 15 % RH	< 10 <sup>6</sup> Ohm
Electrostatic Decay	FTMS 101 method 4046	< 2 sec.
Metal Layer	ETS-803 at 15 % RH	< 100 Ohm
Electrostatic shielding	Energy test EN 61340-5-1	< 50 n J

<u>Chemical Properties</u>	<u>Test Method</u>	<u>Specifications</u>
Contact Corrosivity	FTMS 101C method 3005	no visible sign after testing of deterioration
Ion Content	(Sodium, Fluoride, Phosphate, & Sulfate Ions)	Below Detectable Levels
Amines & Amide Free		

The values shown above were developed from random samples taken from production material we believe them to be typical for the product. However, actual values may vary somewhat from those depicted here and EL.BO. Service makes no warranty, expressed or implied, as to the suitability of these materials for any specific use. Customers should determine product suitability based upon their own internal criteria. Nothing herein is to be taken as a license to operate under or a recommendation to infringe upon any patent.

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